



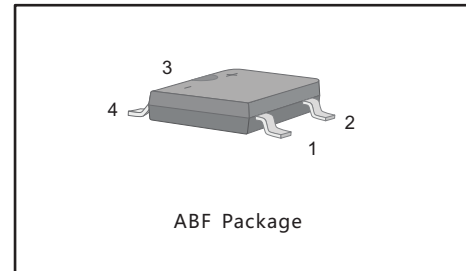
0.8A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

FEATURES:

- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000 V
- Forward Current - 0.8 A
- High Surge Current Capability
- Designed for Surface Mount Application

PINNING

PIN	DESCRIPTION
1	Input Pin ( ~ )
2	Input Pin ( ~ )
3	Output Anode ( + )
4	Output Cathode ( - )



MECHANICAL DATA

- Case: ABF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 82mg 0.0029oz

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	TB1F	TB2F	TB4F	TB6F	TB8F	TB10F	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_c = 125\text{ }^\circ\text{C}$	$I_o$	0.8						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	$I_{FSM}$	30						A
Forward Voltage per element @ $I_F = 0.4\text{ A}$ @ $I_F = 0.8\text{ A}$	$V_F$	1.0 1.1						V
Maximum DC Reverse Current at Rated DC Blocking Voltage @ $T_A = 25\text{ }^\circ\text{C}$ @ $T_A = 100\text{ }^\circ\text{C}$ @ $T_A = 125\text{ }^\circ\text{C}$	$I_R$	5 50 100						$\mu\text{A}$
Typical Thermal Resistance ( Note2 )	$R_{\theta JA}$ $R_{\theta JC}$	80 25						$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55 ~ +150						$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" ( 3.81×3.81 cm ) copper pad.



Fig.1 Average Rectified Output Current Derating Curve

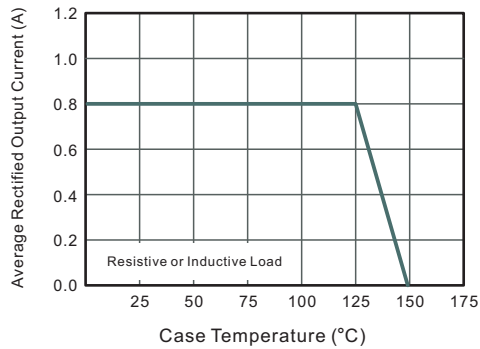


Fig.2 Typical Reverse Characteristics

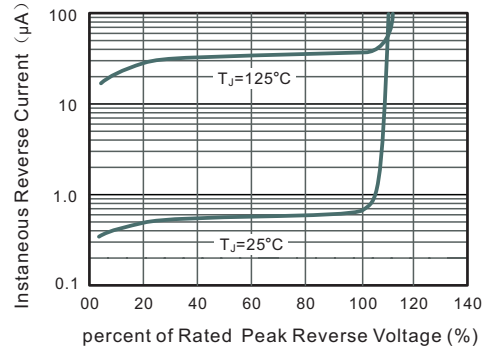


Fig.3 Typical Instantaneous Forward Characteristics

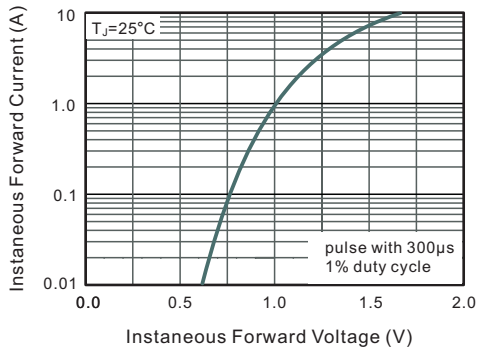
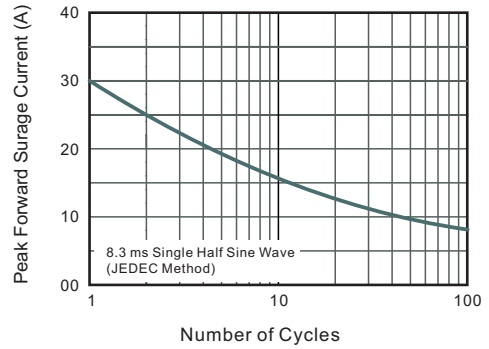


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

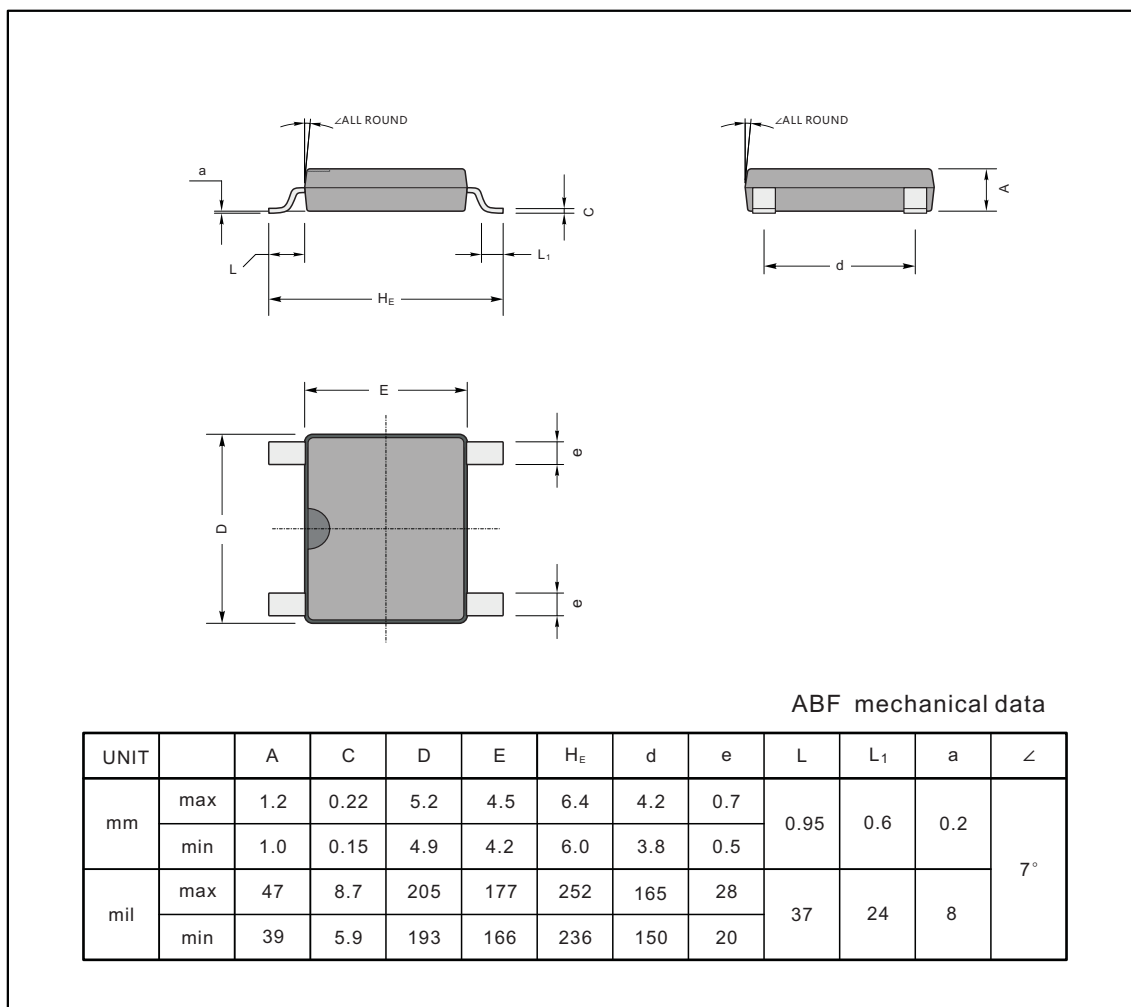




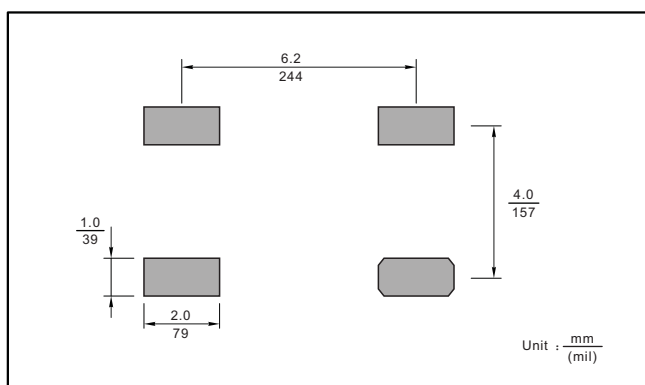
## PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

ABF



### The recommended mounting pad size



### Marking

Type number	Marking code
TB1F	TB1F
TB2F	TB2F
TB4F	TB4F
TB6F	TB6F
TB8F	TB8F
TB10F	TB10F

单击下面可查看定价，库存，交付和生命周期等信息

[>>JINGDAO\(晶导微\)](#)